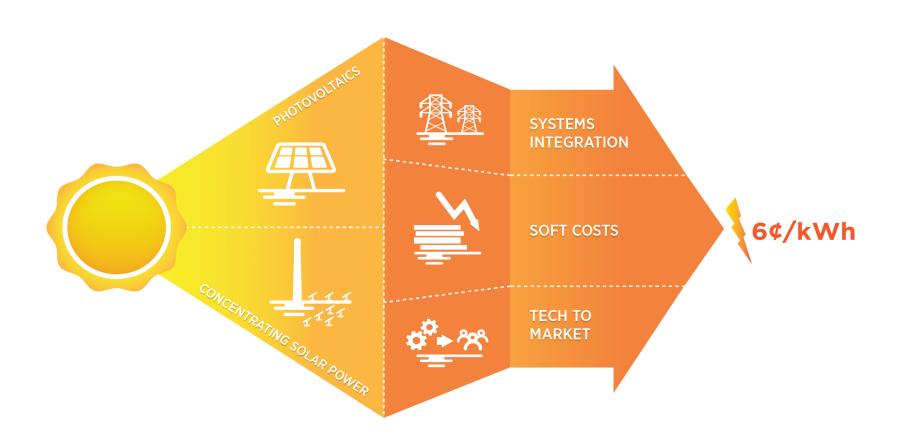


## Developing Next Generation Power Electronics to Enable 100s GW of Solar

### **SunShot Initiative**

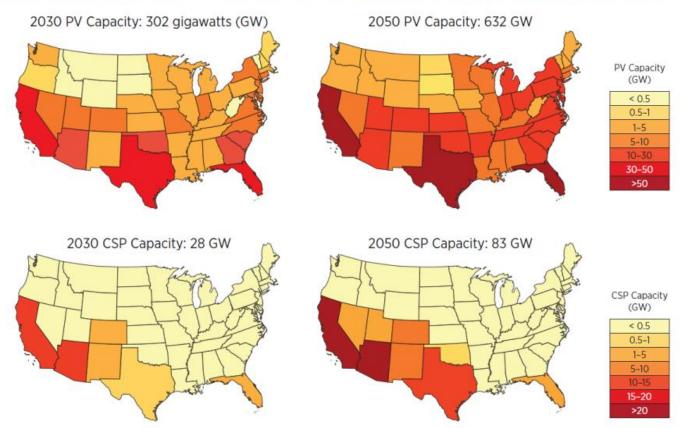


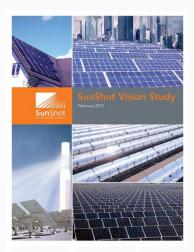


## **SunShot Vision on Deployment**

Solar can meet <u>14% (300GW)</u> by 2030 and <u>27% (600 GW)</u> by 2050 of U.S. electricity demand

#### Cumulative Installed PV and CSP in the SunShot Scenario in 2030 and 2050

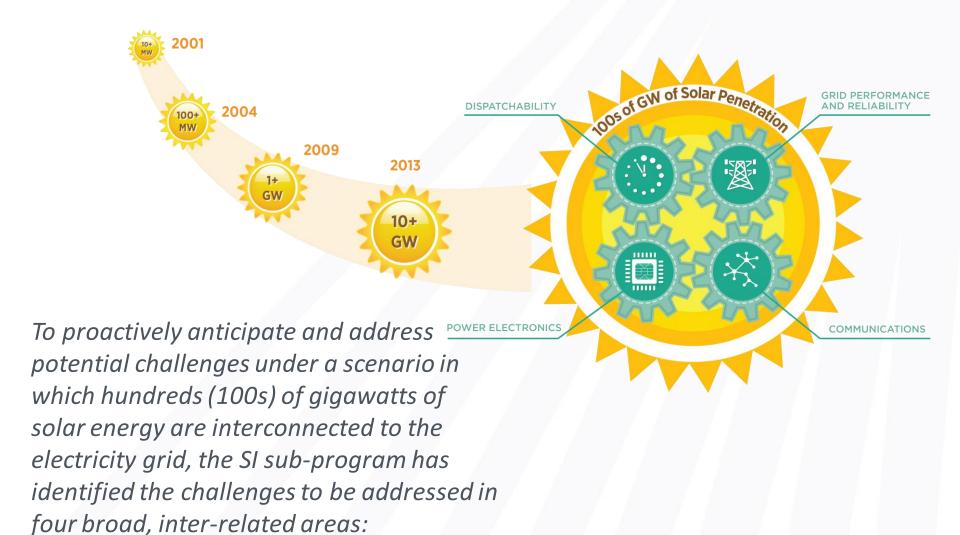




DOE SunShot Vision Study (2012)



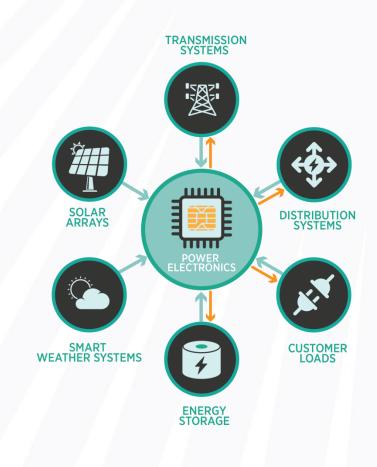
## **SunShot Systems Integration Vision**



## **Topic 3: Power Electronics and Control**

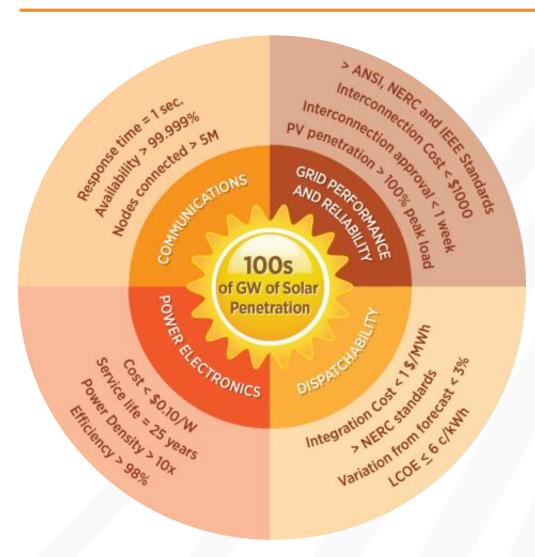
Develop intelligent devices that maximize the power output from solar power plants and interface with the electric grid (or end use circuits), while ensuring overall system performance, safety, reliability, and controllability at minimum cost.

Power Electronics Target Metrics								
Attribute	Target Metric							
Conversion Efficiency	> 98%							
Service Life and Reliability	> 25 years							
Power Density	> 100 W/in <sup>3</sup> for residential and small commercial systems							
System Cost	< \$0.10/W, utility scale < \$0.125/W, commercial scale < \$0.15/W, residential scale							
Grid-Support Functions	Compliance with ANSI, IEEE, and NERC standards <sup>,,</sup>							
Interoperability	Compliance with Open Standards which include SunSpec Modbus, Smart Energy Profile (SEP 2), IEC 61850, MultiSpeak, and DNP3							





## **SunShot Systems Integration**



ENERGISE (2016)

**SuNLaMP (2015)** 

**SHINES (2015)** 

**SUNRISE (2013)** 

National Lab R&D (2012)

Hi-Pen (2012)

Plug and Play (2012)

Solar Forecasting (2012)

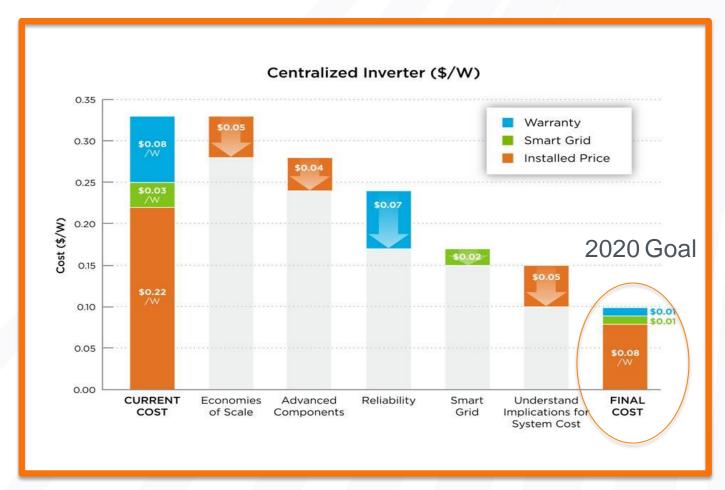
**SEGIS-AC (2011)** 



#### **Solar Energy Grid Integration Systems – Advanced Concepts**

Topic 1: Smart grid functionality that makes it easier to integrate PV solar into the grid

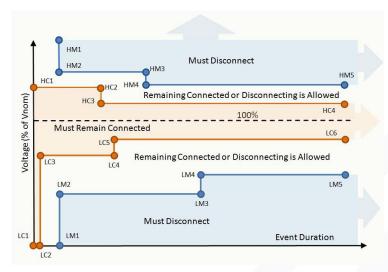
Topic 2: Reduce system cost through innovations in power electronics



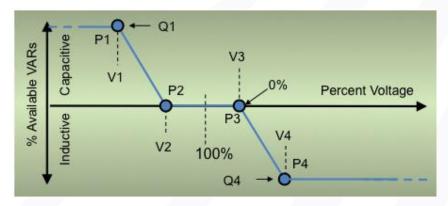


## **Smart Inverter Functions**

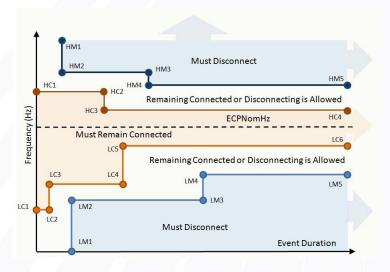
(SEGIS-AC)



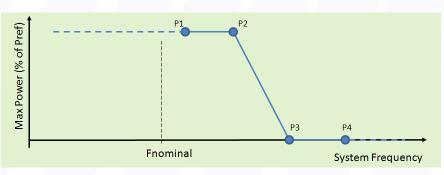
(a) Voltage Ride Through



(c) Volt/Var



(b) Frequency Ride Through



(d) Frequency/Watt



## **Inverter Lab Testing**

- Manufacturer lab testing
- Power HIL Modeling real feeder topology
- Using real event data

#### **NREL ESIF**





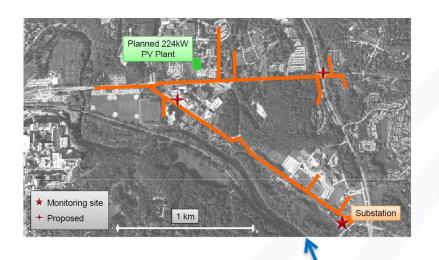
- Grid simulator
- PV simulator
- Communication
- Remote control

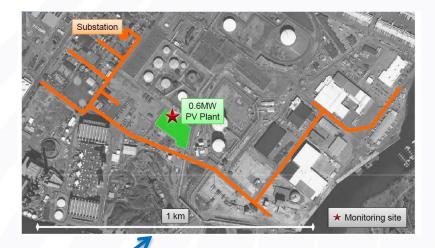


**EPRI Knoxville Lab** 



## **Field Demonstration with Utility Partners**







- Instrumentation
- Inverter upgrade
- PMC
- Communication
- DERMS software
- Remote control



## **Power Electronics Design Improvement**

#### Alencon



- Up to 25kW
- String-wise MPPT
  300 to 1,000V DC Input Voltage
  2,500V DC Bi-polar Output Voltage
  "Plug and Play" Topology

  - Wireless Communication and Data Collection

#### Distributed Harvesting



- •Power Factor Control +/- 0.9 -2,500VDC
- Low/Zero Voltage Ride Through Compact Design

•99.1% Efficient Inverter System

- ·Liquid Cooling Hot-Swap Capability
- ·Lower Total Cost of Ownership
- ·Large BOS System Savings

Designed to be "Made in the USA"

#### Delphi



#### SunPower/SolarBridge



#### Yaskawa/Solectria





## **Power Electronics for Solar**

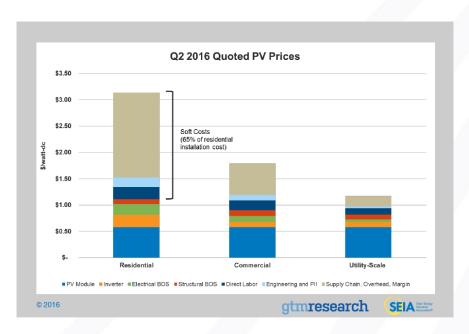
THE NEXT 10 YEARS



#### Growth of Solar in the U.S.

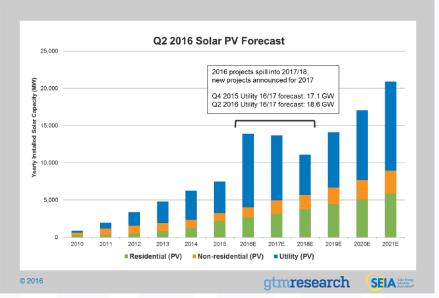
Installed cost of solar system rapidly decreasing

< \$1.5/W for utility-scale system



Installed solar generation capacity rapid increasing

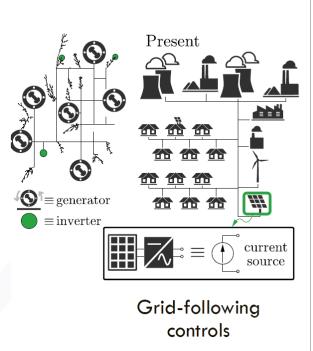
- > 40 GW cumulative by 2016 (projected)
- > 20 GW annual installation by 2021

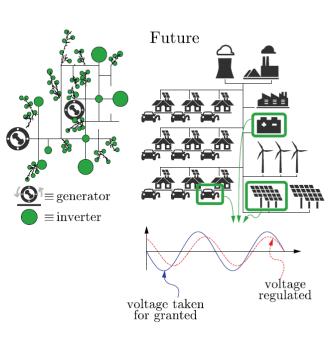




#### **Vision**

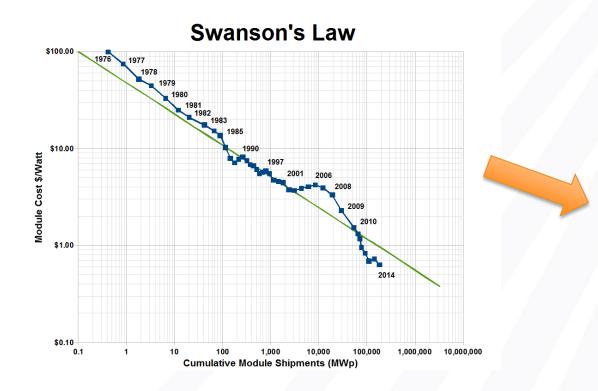
# In 2030, **80%** of electricity could flow through power electronics.





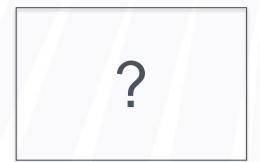


## **The Learning Curves**



the price of solar photovoltaic modules tends to drop 20 percent for every doubling of cumulative shipped volume

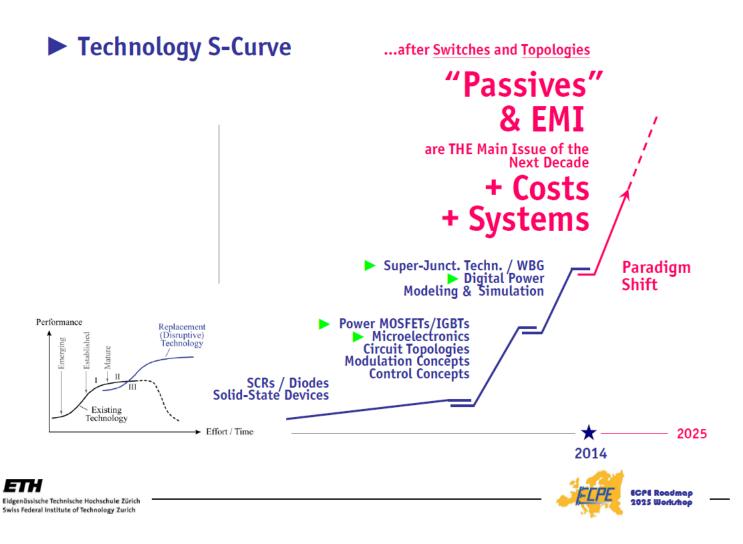
## Power Electronics (More-than-Moore?)





#### Where are we on the S-Curve?

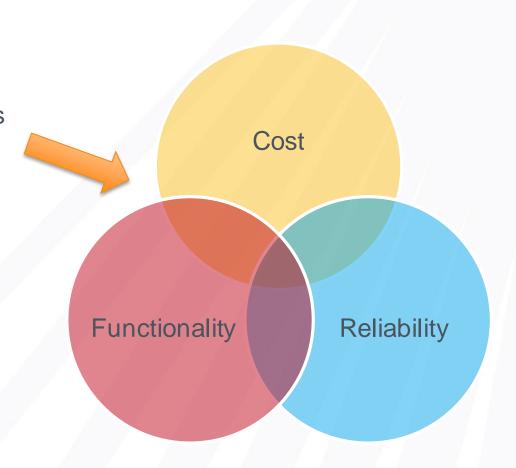
Johann W. Kolar, "Vision – Power Electronics 2025"





## **How to Balance Trade-offs**

- Manufacturers
- PV developers
- Owners & Operators
- Utilities





## **Technology Roadmaps**

WBG Devices HF magnetics Additive Manufacturing

Controls Thermal Management Mechanical Design

EMI Circuit Topology Passives

## PowerAmerica Silicon Carbide Roadmap Drives Long Term Strategy

	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	
I	AEC-Q101 qual high-l <sub>DS</sub> chips	175°C is T <sub>Jmax</sub> for qual	650V – 175A chip @ 90C	1.2kV – 150A chip @ 90C	1.7kV – 125A chip @ 90C	2.4kV – 100A chip @ 90C	3.3kV – 50A chip @ 90C	4.5kV – 40A chip @ 90C	6.5kV – 30A chip @ 90C	6.5kV – 60A IGBT chip @ 90C	
V	1.2, 1.7 kV SBD/FET	3.3 kV SBD/ FET	2.4kV SBD/ FET	4.5, 6.5 kV SBD/FET	6.5, 10 kV SBD/FET	6.5kV SBD/ IGBT	10 kV PiN Diode/IGBT	15 kV PiN Diode/IGBT	20 kV PiN Diode/IGBT	30 kV PiN Diode/IGBT	
\$	1.2 kV FET 40 c/A	1.2 kV FET 30 c/A	1.2 kV FET 25 c/A	1.2 kV FET 20 c/A	1.2 kV FET 15 c/A	1.2 kV FET	1.2 kV FET	1.2 kV FET	1.2 kV FET	1.2 kV FET	
Арр	PFC, PV 5-10 kW	Power Supply	UPS/HVAC/ SSCB	PV 50-250kW, 1.5kV bus	EV Traction	MV VSD Automotive Chargers	Central PV 1-10 MW	DC dis. Data Servers	Wind	Grid power Flow	
ı	Frequency / Technology										
	40-100kHz LF DMOS	50-500kHz HF DMOS	40-100kHz HF trench	5-10kHz LF trench	10-30kHz LF/HF trench	5-10kHz LF IGBT	5-10kHz LF IGBT	0.1-1.0MHz HF IGBT	5-10kHz LF IGBT	5-10kHz LF IGBT	



## **Other Questions For Workshop Discussions**

- What are most critical challenges and research priorities?
- How do we leverage other industries wind, automotive, energy storage, and industrial motors?
- How to bridge the gap between technology potentials and commercial successes?





## Thank You!

& Let's work together!

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